

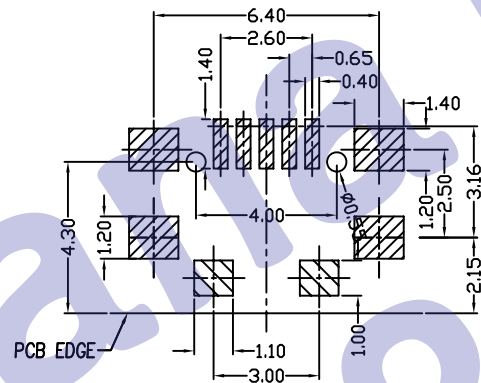
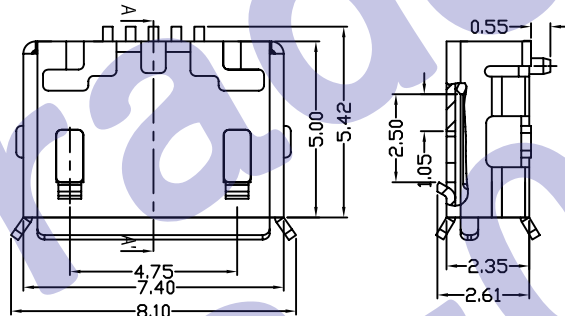
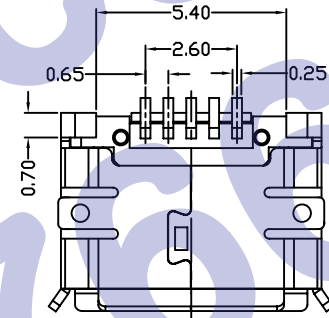
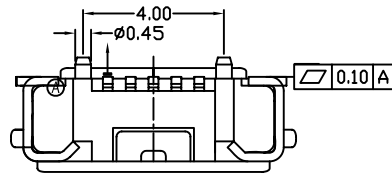
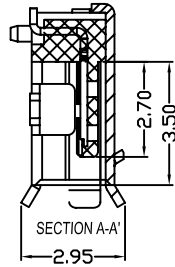
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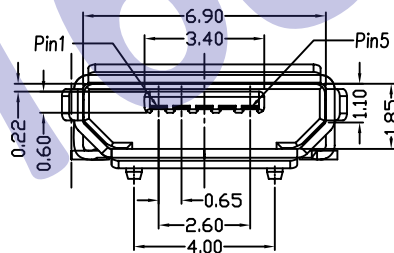
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RECOMMENDED PCB LAYOUT



Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g. f, UL94v-0
- 1.2 Contact: copper alloy, $t=0.20\text{mm}$
- 1.3 Shell: copper alloy, $t=0.25\text{mm}$

2. Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 m Ω Max.
- 2.4 Insulation resistance: 100 M Ω Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
- 2.7 Temperature range: $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$

设计 DRAW BY	杨帆	审核 DISCUSS BY	
校对 DISCUSS BY		比例 SCALE	2:1

HDC有限公司

图名 DRAWING NO	MICRO USB B TYPE SMT 外壳有孔型 有柱	图号 SHEET NO	109	日期 DATE	2011.09.15
料号 VERSION		数量 QUAN		备注 REMARK	张号 SHEET
				版次 REMARK	1/1

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